

Power MOSFET

TO-252

2A, 650V N-CHANNEL SUPER-JUNCTION MOSFET

DESCRIPTION

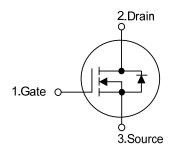
The UTC **2NM65-FDQ** is a Super Junction MOSFET Structure. It uses UTC advanced planar stripe, DMOS technology to provide customers perfect switching performance, minimal on-state resistance.

The UTC **2NM65-FDQ** is universally applied in electronic lamp ballasts based on half bridge topology, high efficiency switched mode power supplies, active power factor correction, etc.

FEATURES

- * $R_{DS(ON)}$ < 3.0 Ω @ V_{GS} = 10V, I_D =1.0A
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

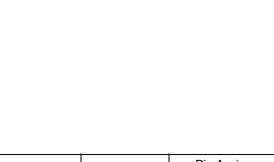
SYMBOL



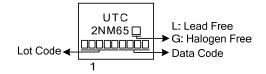
ORDERING INFORMATION

Ordering Number			Deekege	Pin Assignment			Deaking	
	Lead Free	Halogen Free	Package	1	2	3	Packing	
	2NM65L-TN3-R	2NM65G-TN3-R	TO-252	G	D	S	Tape Reel	
Note:	Note: Pin Assignment: G: Gate D: Drain S: Source							

2NM65G- <u>TN3-</u> R	(1)Packing Type	(1) R: Tape Reel					
	(2)Package Type	(2) TN3: TO-252					
	(3)Green Package	(3) G: Halogen Free and Lead Free L: Lead Free	•				
	- (2)Package Type (2) TN3: TO-252						
JC WWW. FIV.							
			4 60				



MARKING





Power MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V _{DSS}	650	V
Gate-Source Voltage		V _{GSS}	±30	V
Drain Current	Continuous	I _D	2	А
	Pulsed (Note 2)	I _{DM}	6	А
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	72	mJ
Peak Diode Recovery	dv/dt (Note 4)			V/ns
Power Dissipation		PD	44	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L=144mH, I_{AS} =1.0A, V_{DD} =50V, R_G =25 Ω , Starting T_J = 25°C

4. I_{SD}≤2.0A, di/dt≤200A/µs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C

THERMAL DATA

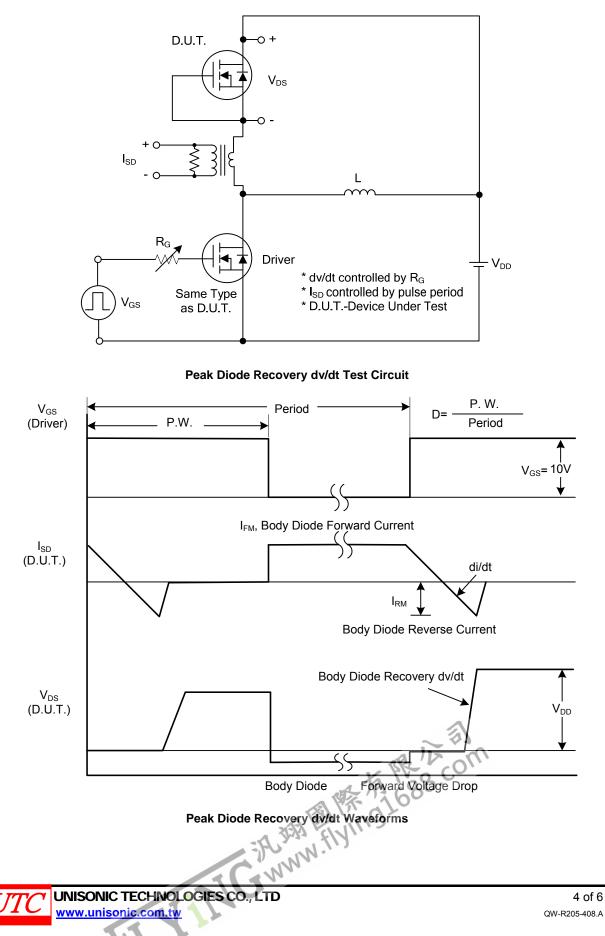
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	100	°C/W
Junction to Case	θ _{JC}	2.8	°C/W

ELECTRICAL CHARACTERISTICS (TJ=25°C, unless otherwise specified)

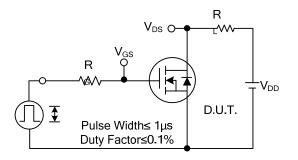
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PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS				-	-		
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} = 0V, I _D = 250µA	650			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} = 650V, V _{GS} = 0V			10	μA
Cata Source Lookage Current	Forward	- I _{GSS}	$V_{GS} = 30V, V_{DS} = 0V$			100	nA
Gate-Source Leakage Current	Reverse		V_{GS} = -30V, V_{DS} = 0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.5	V
Static Drain-Source On-State Re	sistance	R _{DS(ON)}	V _{GS} = 10V, I _D =1.0A			3.0	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ISS}			130		рF
Output Capacitance		C _{OSS}	V _{DS} =25V, V _{GS} =0V, f =1MHz		110		рF
Reverse Transfer Capacitance		C _{RSS}			10		рF
SWITCHING CHARACTERISTIC	S						
Turn-On Delay Time		t _{D (ON)}			1.2		ns
Turn-On Rise Time		t _R	V _{DD} =300V, V _{GS} =10V, I _D =2.0A,		8.4		ns
Turn-Off Delay Time		t _{D(OFF)}	R _G =25Ω (Note 1, 2)		14		ns
Turn-Off Fall Time		t _F			20		ns
DRAIN-SOURCE DIODE CHAR	ACTERISTIC	CS					
Continuous Drain-Source Current		Is				2.0	Α
Maximum Body-Diode Pulsed Current		I _{SM}				6.0	Α
Drain-Source Diode Forward Voltage		V _{SD}	I _S =2.0A, V _{GS} =0V			1.4	V
Body Diode Reverse Recovery Time		t _{rr}	I _S =2.0A, V _{GS} =0V	2	110		nS
Body Diode Reverse Recovery C	harge	Q _{rr}	dl/dt=100A/µs		0.4		μC
Notes: 1. Pulse Test: Pulse width	i ≤ 300µs, D	uty cycle≤2%.	1 18 (20.				
2. Essentially independen	t of operatin	g temperature.	A 17. 10				
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		500	N				
		CINN	*				
Body Diode Reverse Recovery Charge Qrr dl/dt=100A/µs Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle≤2%. 2. Essentially independent of operating temperature. 2. Essentially independent of operating temperature. 0 UNISONIC TECHNOLOGIES CO., LTD						÷	3 of 6



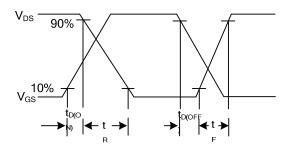
TEST CIRCUITS AND WAVEFORMS



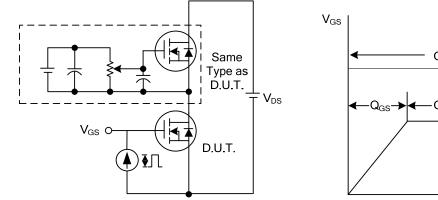
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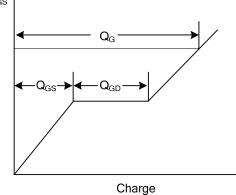
Switching Test Circuit



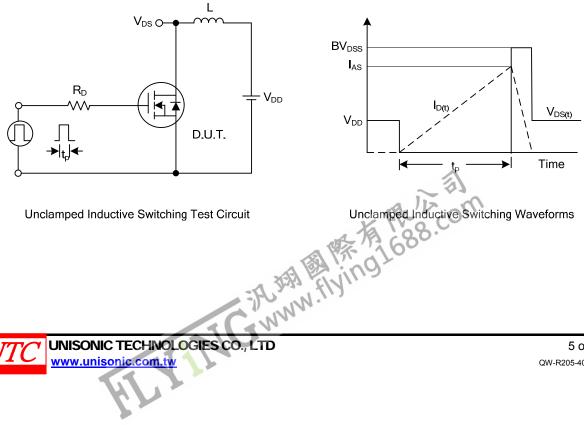
Switching Waveforms



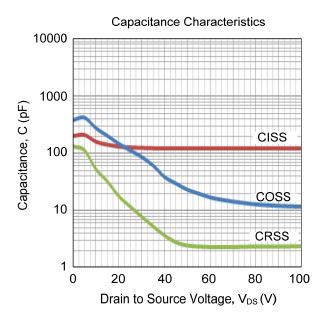
Gate Charge Test Circuit



Gate Charge Waveform



TYPICAL CHARACTERISTICS



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